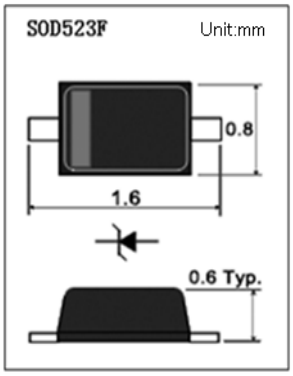
- ◇ Low Forward Voltage Drop
- ◇ **SOD523** Micro SMD Package
- ◇ RoHS Compliant / Green EMC
- ◇ Matte Tin (Sn) Lead Finish
- ◇ Cathode Band / Device Marking
- ◇ Surface Mount Package Ideally Suited For Automatic Insertion



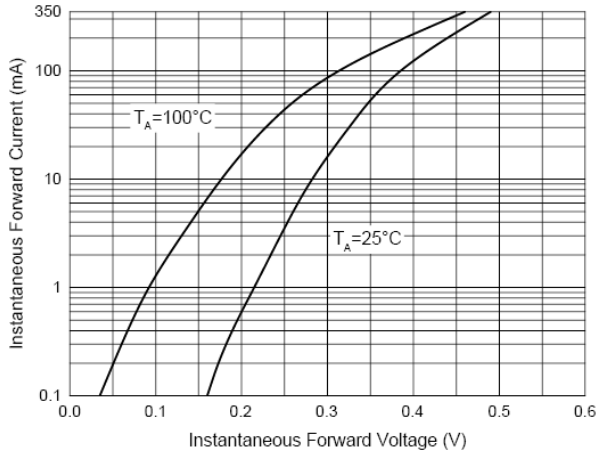
Maximum Ratings (Ta = 25 ℃)

Symbol	Parameter	Value	Units
V_{RRM}	Peak Repetive Reverse Voltage	40	V
V_{RWM}	Working Peak Reverse Voltage	40	V
V_R	DC Blocking Voltage	40	V
$V_{R(RMS)}$	RMS Reverse Voltage	28	V
I_{FM}	Forward Continuous Current	350	mA
I_{FSM}	Non-Repetitive Peak Forward Surge Current (@t=8..3ms)	2.0	A
P_D	Power Dissipation	200	mW
T_J	Junction Temperature	125	℃
T_{STG}	Storage Temperature	-55 to +150	℃
$R_{\theta JA}$	Thermal Resistance From Junction To Ambient	625	℃/W

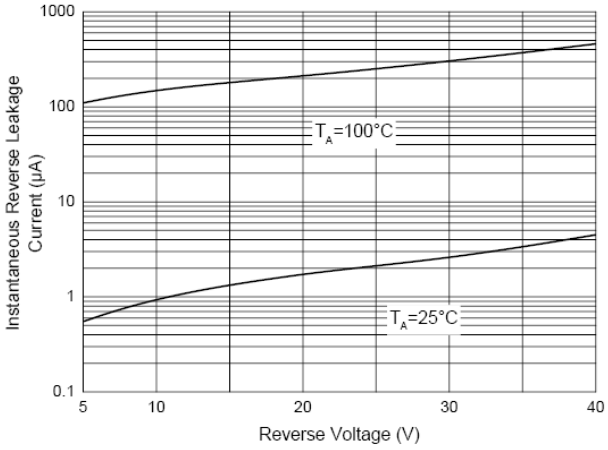
Electrical Characteristics (Ta = 25 ℃)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
V_{BR}	Reverse Voltage	I_F = 100uA	40			V
V_F	Forward Voltage	I_F = 20mA I_F = 200mA			0.37 0.60	V V
I_R	Reverse current	V_R= 30V			5	μA
C_T	Capacitance	V_R = 0V, f = 1MHz			50	pF
t_{rr}	Typical Reverse Recovery Time	I_F = I_R =200mA, Irr=0.1*I_R, R_L = 100Ω		10		ns

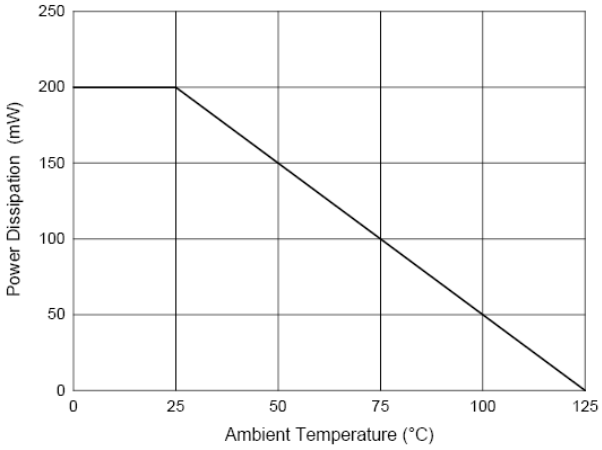
Curve Characteristics



Typical Instantaneous Forward Characteristics



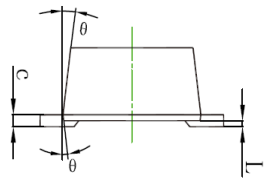
Typical Reverse Leakage Characteristics

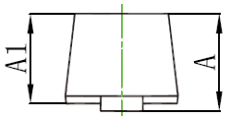


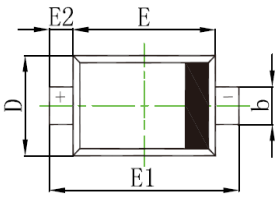
Power Derating Curve

Package Dimensions

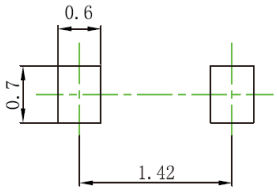
Package outline : SOD-523







SOD523Package Outline



Land Pattern Recommendation

Unit	A	A1	b	c	D	E	E1	E2	L	θ
Max.	0.70	0.70	0.35	0.15	0.85	1.30	1.70	0.25	0.07	7° REF.
Min.	0.51	0.50	0.25	0.08	0.75	1.10	1.50	0.15	0.01	

Note:
1. Halogen free,EMC
2. Pb free solder
3. Lead thickness includes solder plating
4. Lead frame: Cu
5. Other Tolerance: ±0.05
6. Dimensions are exclusive of Burrs,Mold Flash and Tie Bar extrusions
7. Unit: mm